**MARKING** 

# **Noninverting 3-State Buffer**

# **NLV74VHC1G126**, NLV74VHC1GT126

The NLV74VHC1G126 / NLV74VHC1GT126 is a single gate noninverting 3-state buffer in tiny footprint packages. The NLV74VHC1G126 has CMOS-level input thresholds while the NLV74VHC1GT126 has TTL-level input thresholds.

The internal circuit is composed of three stages, including a buffered 3-state output which provides high noise immunity and stable output.

The input structures provide protection when voltages up to 5.5 V are applied, regardless of the supply voltage. This allows the device to be used to interface 5 V circuits to 3 V circuits. Some output structures also provide protection when  $V_{CC} = 0$  V and when the output voltage exceeds V<sub>CC</sub>. These input and output structures help prevent device destruction caused by supply voltage - input/output voltage mismatch, battery backup, hot insertion, etc.

#### **Features**

- Designed for 2.0 V to 5.5 V V<sub>CC</sub> Operation
- 3.5 ns t<sub>PD</sub> at 5 V (typ)
- Inputs/Outputs Over-Voltage Tolerant up to 5.5 V
- I<sub>OFF</sub> Supports Partial Power Down Protection
- Source/Sink 8 mA at 3.0 V
- Available in SC-88A, TSOP-5 and SOT-953 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

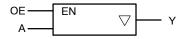


Figure 1. Logic Symbol

# **DIAGRAMS** SC-88A XX M= **DF SUFFIX CASE 419A** TSOP-5 **DT SUFFIX CASE 483**

= Specific Device Code XX

Μ

SOT-953

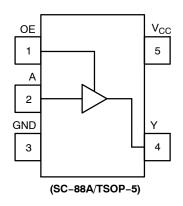
P5 SUFFIX CASE 527AE

= Date Code\* = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 8 of this data sheet.



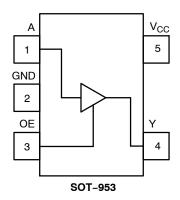


Figure 2. Pinout (Top View)

# PIN ASSIGNMENT (SC-88A/TSOP-5)

Pin	Function
1	OE
2	Α
3	GND
4	Υ
5	V <sub>CC</sub>

### PIN ASSIGNMENT (SOT-953)

Pin	Function
1	Α
2	GND
3	OE
4	Y
5	V <sub>CC</sub>

#### **FUNCTION TABLE**

Inp	Output	
OE	Α	Υ
Н	L	L
Н	Н	Н
L	X	Z

X = Don't Care

#### **MAXIMUM RATINGS**

Symbol		Characteristics	Value	Unit		
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V			
V <sub>IN</sub>	DC Input Voltage	DC Input Voltage				
V <sub>OUT</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V			
		1GTxx Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V <sub>CC</sub> = 0 V)	-0.5 to V <sub>CC</sub> + 0.5 -0.5 to +7.0 -0.5 to +7.0			
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA		
I <sub>OK</sub>	DC Output Diode Current	1Gxx V <sub>OUT</sub> > V <sub>CC</sub> , V <sub>OUT</sub> < GND	±20	mA		
		1GTxx V <sub>OUT</sub> < GND	-20	1		
I <sub>OUT</sub>	DC Output Source/Sink Current		±25	mA		
I <sub>CC</sub> or I <sub>GND</sub>	DC Supply Current per Supply F	±50	mA			
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C			
TL	Lead Temperature, 1 mm from 0	Case for 10 secs	260	°C		
TJ	Junction Temperature Under Bia	as	+150	°C		
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SC-88A TSOP-5 SOT-953	377 320 254	°C/W		
P <sub>D</sub>	Power Dissipation in Still Air	332 390 491	mW			
MSL	Moisture Sensitivity		Level 1	-		
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-		
V <sub>ESD</sub>	ESD Withstand Voltage (Note 3	Human Body Model Charged Device Model	2000 1000	V		
I <sub>Latchup</sub>	Latchup Performance (Note 4)		±100	mA		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri–stated.

Applicable to devices with outputs that may be th-stated.
 Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
 Tested to EIA/JESD78 Class II.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Cł	Min	Max	Unit	
V <sub>CC</sub>	Positive DC Supply Voltage		2.0	5.5	V
$V_{IN}$	DC Input Voltage	0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage	1Gxx	0	V <sub>CC</sub>	V
		1GTxx Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V <sub>CC</sub> = 0 V)	0 0 0	V <sub>CC</sub> 5.5 5.5	
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$ $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS (NLV74VHC1G126)

		Test	v <sub>cc</sub>	1	Γ <sub>A</sub> = 25°	С	-40°C ≤	Γ <sub>A</sub> ≤ 85°C	-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input		2.0	1.5	-	-	1.5	-	1.5	-	V
	Voltage		3.0	2.1	-	-	2.1	-	2.1	-	
			4.5	3.15	_	_	3.15	-	3.15	-	
			5.5	3.85	_	-	3.85	_	3.85	-	
V <sub>IL</sub>	Low-Level Input		2.0	-	_	0.5	-	0.5	-	0.5	V
	Voltage		3.0	_	_	0.9	-	0.9	-	0.9	
			4.5	-	_	1.35	-	1.35	-	1.35	
			5.5	-	-	1.65	=	1.65	-	1.65	
V <sub>OH</sub>	High-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OH} = -50  \mu\text{A} \\ &I_{OH} = -50  \mu\text{A} \\ &I_{OH} = -50  \mu\text{A} \\ &I_{OH} = -4  m\text{A} \\ &I_{OH} = -8  m\text{A} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	1.9 2.9 4.4 2.58 3.94	2.0 3.0 4.5 –		1.9 2.9 4.4 2.48 3.80	- - - -	1.9 2.9 4.4 2.34 3.66	- - - -	V
V <sub>OL</sub>	Low-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	- - - -	0.0 0.0 0.0 - -	0.1 0.1 0.1 0.36 0.36	- - - -	0.1 0.1 0.1 0.44 0.44	- - - -	0.1 0.1 0.1 0.52 0.52	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	2.0 to 5.5	-	_	±0.1	-	±1.0	-	±1.0	μΑ
I <sub>OZ</sub>	3-State Output Leakage Current	V <sub>OUT</sub> = 0 V to 5.5 V	5.5	-	_	±0.25	-	±2.5	_	±2.5	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V	0.0	_	_	1.0	-	10	_	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	_	_	1.0	-	20	-	40	μΑ

# DC ELECTRICAL CHARACTERISTICS (NLV74VHC1GT126)

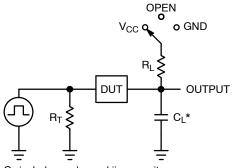
		Test	$v_{cc}$	1	Γ <sub>A</sub> = 25°	C	-40°C ≤	Γ <sub>A</sub> ≤ 85°C	$-55$ °C ≤ $T_A$ ≤ 125°C		
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input		2.0	1.0	-	-	1.0	-	1.0	-	V
	Voltage		3.0	1.4	_	-	1.4	_	1.4	_	
			4.5	2.0	_	-	2.0	_	2.0	-	
			5.5	2.0	_	-	2.0	_	2.0	_	
V <sub>IL</sub>	Low-Level Input		2.0	-	-	0.28	-	0.28	-	0.28	V
	Voltage		3.0	-	-	0.45	-	0.45	-	0.45	
			4.5	-	_	0.8	-	0.8	-	0.8	
			5.5	-	_	0.8	-	0.8	-	0.8	
V <sub>OH</sub>	High-Level Output Voltage	$\begin{aligned} V_{IN} &= V_{IH} \text{ or } V_{IL} \\ I_{OH} &= -50  \mu\text{A} \\ I_{OH} &= -50  \mu\text{A} \\ I_{OH} &= -50  \mu\text{A} \\ I_{OH} &= -4 \text{ mA} \\ I_{OH} &= -8 \text{ mA} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	1.9 2.9 4.4 2.58 3.94	2.0 3.0 4.5 –	- - - -	1.9 2.9 4.4 2.48 3.80		1.9 2.9 4.4 2.34 3.66	- - - -	V
V <sub>OL</sub>	Low-Level Output Voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 50  \mu\text{A} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \end{aligned}$	2.0 3.0 4.5 3.0 4.5	- - - -	0.0 0.0 0.0 - -	0.1 0.1 0.1 0.36 0.36	1 1 1 1	0.1 0.1 0.1 0.44 0.44	- - - -	0.1 0.1 0.1 0.52 0.52	V
I <sub>IN</sub>	Input Leakage Cur- rent	V <sub>IN</sub> = 5.5 V or GND	2.0 to 5.5	-	-	±0.1	-	±1.0	_	±1.0	μΑ
I <sub>OZ</sub>	3-State Output Leakage Current	V <sub>OUT</sub> = 0 V to 5.5 V	5.5	-	-	±0.25	-	±2.5	_	±2.5	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0	_	_	1.0	-	10	-	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	-	_	1.0	-	20	_	40	μΑ
I <sub>CCT</sub>	Increase in Quies- cent Supply Current per Input Pin	One Input: V <sub>IN</sub> = 3.4 V; Other Input at V <sub>CC</sub> or GND	5.5	-	-	1.35	-	1.5	-	1.65	mA

#### **AC ELECTRICAL CHARACTERISTICS**

				T	A = 25°	С	-40°C ≤ 7	Γ <sub>A</sub> ≤ 85°C	-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay,	C <sub>L</sub> = 15 pF	3.0 to 3.6	_	4.5	8.0	-	9.5	_	12.0	ns
t <sub>PHL</sub>	A to Y (Figures 3 and 4)	C <sub>L</sub> = 50 pF		_	6.4	11.5	-	13.0	_	16.0	
	,	C <sub>L</sub> = 15 pF	4.5 to 5.5	_	3.5	5.5	-	6.5	_	8.5	
		C <sub>L</sub> = 50 pF		_	4.5	7.5	-	8.5	_	10.5	
t <sub>PZL</sub> ,	Output Enable	C <sub>L</sub> = 15 pF	3.0 to 3.6	_	4.5	8.0	-	9.5	_	11.5	ns
t <sub>PZH</sub>	Time, OE to Y (Figures 3 and 4)	C <sub>L</sub> = 50 pF		_	6.4	11.5	-	13.0	_	15.0	
	,	C <sub>L</sub> = 15 pF	4.5 to 5.5	-	3.5	5.1	-	6.0	_	8.5	
		C <sub>L</sub> = 50 pF		_	4.5	7.1	-	8.0	_	10.5	
t <sub>PLZ</sub> ,	Output Disable	C <sub>L</sub> = 15 pF	3.0 to 3.6	-	6.5	9.7	-	11.5	_	14.5	ns
t <sub>PHZ</sub>	Time, OE to Y (Figures 3 and 4)	C <sub>L</sub> = 50 pF		_	8.0	13.2	-	15.0	_	18.0	
	,	C <sub>L</sub> = 15 pF	4.5 to 5.5	_	4.8	6.8	-	8.0	_	10.0	
		C <sub>L</sub> = 50 pF		_	7.0	8.8	-	10.0	_	12.0	
C <sub>IN</sub>	Input Capacitance			_	4.0	10	-	10	_	10	pF
C <sub>OUT</sub>	Output Capacitance	Output in High Impedance State		-	6.0	ı	-	-	-	-	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	8.0	pF

<sup>5.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.



Test	Switch Position	C <sub>L</sub> , pF	$R_L, \Omega$
t <sub>PLH</sub> / t <sub>PHL</sub>	Open	See AC Characteristics Table	Х
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>CC</sub>		1 k
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND		1 k

X = Don't Care

 $C_L$  includes probe and jig capacitance  $R_T$  is  $Z_{OUT}$  of pulse generator (typically 50  $\Omega)$  f = 1 MHz

Figure 3. Test Circuit

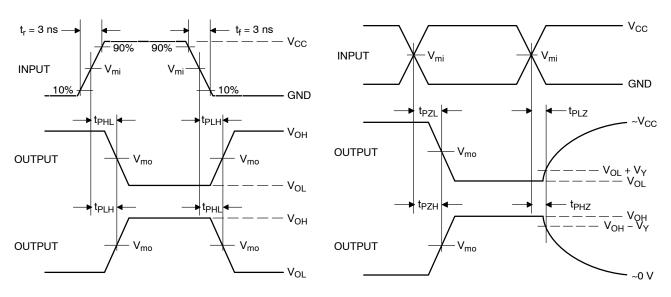


Figure 4. Switching Waveforms

		V <sub>m</sub>		
V <sub>CC</sub> , V	V <sub>mi</sub> , V	t <sub>PLH</sub> , t <sub>PHL</sub>	$t_{PZL}$ , $t_{PLZ}$ , $t_{PZH}$ , $t_{PHZ}$	V <sub>Y</sub> , V
3.0 to 3.6	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3
4.5 to 5.5	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3

#### **ORDERING INFORMATION**

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
M74VHC1G126DFT2G-L22038	SC-88A	W2	Q4	3000 / Tape & Reel
NLVVHC1G126DFT1G*	SC-88A	W2	Q2	3000 / Tape & Reel
NLVVHC1G126DFT2G*	SC-88A	W2	Q4	3000 / Tape & Reel
M74VHC1GT126DF1G-L22038	SC-88A	W3	Q2	3000 / Tape & Reel
NLVVHC1GT126DF2G*	SC-88A	W3	Q4	3000 / Tape & Reel
NLVVHC1GT126DF1G*	SC-88A	W3	Q2	3000 / Tape & Reel
M74VHC1G126DTT1G	TSOP-5	W2	Q4	3000 / Tape & Reel
M74VHC1GT126DT1G	TSOP-5	W3	Q4	3000 / Tape & Reel
NLVVHC1GT126DT1G*	TSOP-5	W3R	Q4	3000 / Tape & Reel
MC74VHC1G126P5T5G-L22088	SOT-953	J	Q2	8000 / Tape & Reel
MC74VHC1GT126P5T5G-L22088	SOT-953	R	Q2	8000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### Pin 1 Orientation in Tape and Reel

### **Direction of Feed**





<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

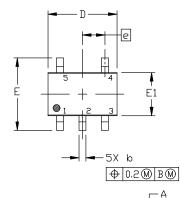
#### **PACKAGE DIMENSIONS**

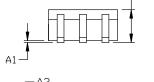
#### SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

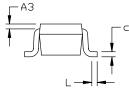
#### NDTES:

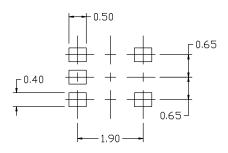
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSOLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
  OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MILLIMETERS			
	MIN.	N□M.	MAX.	
Α	0.80	0.95	1.10	
A1			0.10	
A3	0.20 REF			
b	0.10	0.20	0.30	
C	0.10		0,25	
D	1.80	2.00	2.20	
Е	2.00	2.10	2.20	
E1	1.15	1.25	1.35	
е	0.65 BSC			
L	0.10	0.15	0.30	







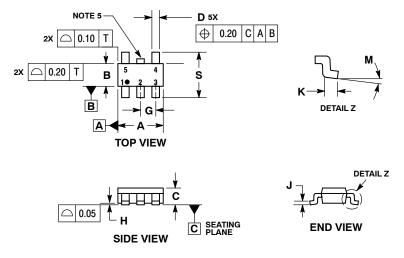


# RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

#### **PACKAGE DIMENSIONS**

TSOP-5 CASE 483-02 **ISSUE N** 

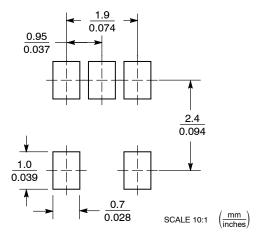


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
   MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
   DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
   OPTIONAL CONSTRUCTION: AN ADDITIONAL
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α	2.85	3.15	
В	1.35	1.65	
С	0.90	1.10	
D	0.25	0.50	
G	0.95 BSC		
Н	0.01	0.10	
J	0.10	0.26	
Κ	0.20	0.60	
М	0 °	10 °	
S	2.50	3.00	

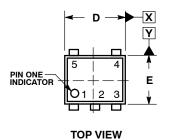
#### **SOLDERING FOOTPRINT\***

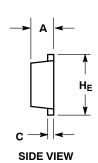


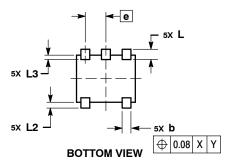
\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### SOT-953 CASE 527AE **ISSUE E**





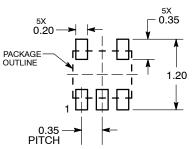


#### NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- CONTROLLING DIMENSION: MILLIMETERS
  MAXIMUM LEAD THICKNESS INCLUDES LEAD
  FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
E	0.75	0.80	0.85	
е	0.35 BSC			
HE	0.95	1.00	1.05	
L		0.175 REF		
L2	0.05	0.10	0.15	
L3			0.15	

#### **SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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